

# OL-PCA85233

Bare die; 110 bumps

10 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	U (upper)
<b>Package type descriptive code</b>	UC
<b>Package type industry code</b>	UC
<b>Package style descriptive code</b>	UC (uncased chip)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	X (other)
<b>IEC package outline code</b>	---
<b>JEDEC package outline code</b>	---
<b>JEITA package outline code</b>	---
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	6-9-2011

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
e	nominal pitch	-	-	0	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	110	-	



## 2. Package outline

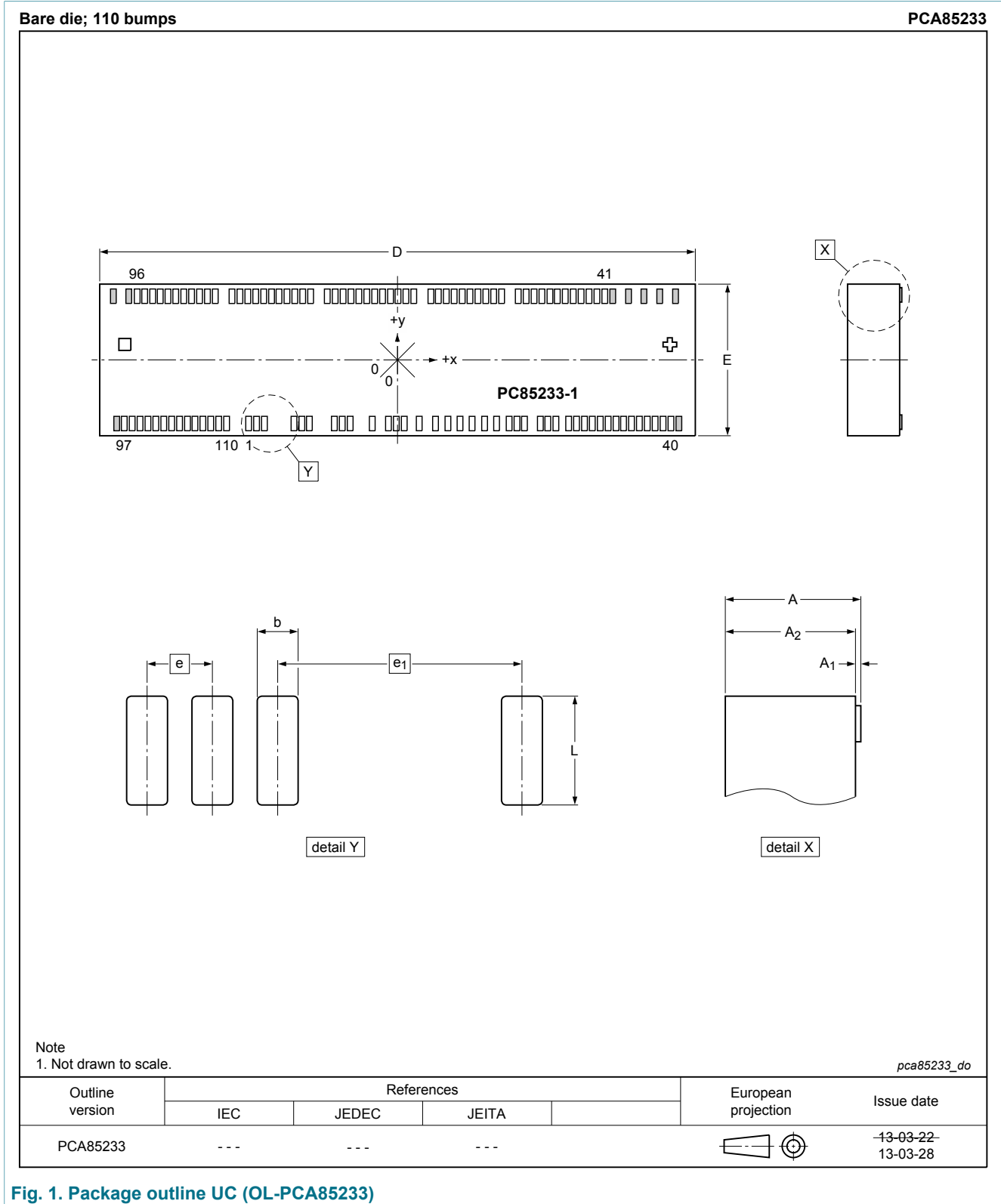


Fig. 1. Package outline UC (OL-PCA85233)

### 3. Legal information

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